

Product Change Notification

Control No. PCN-11111

March 15, 2011

Type of Change: Design: Manufacturing Other

We are providing you this notification in accordance with Power Integrations policy of critical change notification. If you have any questions or need further assistance, please contact the PI Sales office serving your geographic location.

DESCRIPTION OF THE CHANGE: The pin configuration of all products in eDIP and eSOP packages is being modified. The modification is to eliminate an unconnected pin (pin 5) in order to improve creepage between the high-voltage pin (pin 6) and the adjacent pin. See the figures below for illustration of the changes.

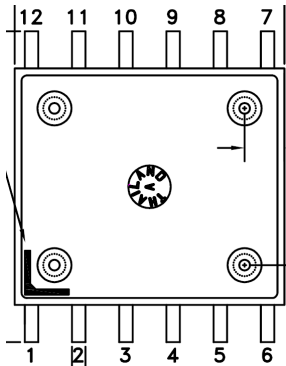


Fig. 1 (a) Top view of eSOP (K) package with the current pin-out configuration.

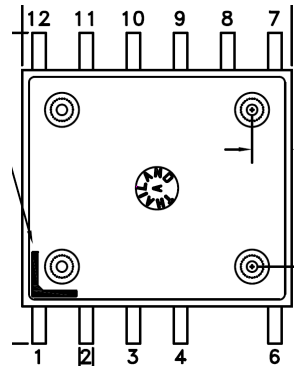


Fig. 1 (b) Top view of eSOP (K) package with the new pin-out configuration

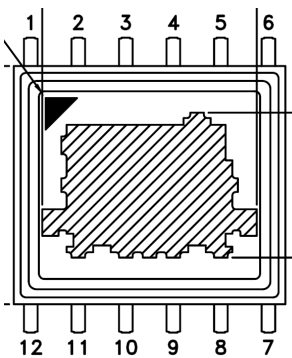


Fig. 2 (a) Top view of eDIP (V) package with the current pin-out configuration.

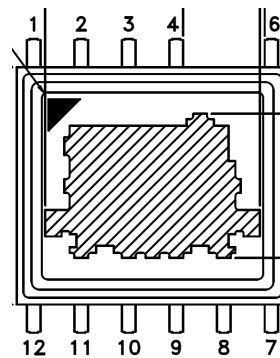


Fig. 2 (b) Top view of eDIP (V) package with the new pin-out configuration

CONFIDENTIAL: The information in this report contains confidential and proprietary information of Power Integrations and its manufacturing partners. By receiving this report, the customer agrees to use this information for the sole purpose of addressing the issues reviewed in this report and to keep the report's contents confidential. If it becomes necessary for the customer to disclose this information to a third party, a non-disclosure agreement, which provides reasonable and customary protection for the disclosed information, must be executed.

EFFECT ON CUSTOMER: There is no negative impact. Customer may need to adjust the incoming inspection procedure so that products with the new pin configuration are accepted as well as those with the old pin configuration. Products with the old pin configuration may continue to be shipped after the effective date as long as the supply lasts.

EFFECT ON PRODUCT QUALITY: None. There is no effect on product parameter limits as published in the data sheet. Other than the omitted pin, the package dimensions and the package footprint will remain the same.

PRODUCTS AFFECTED: All of the current products in eDIP (V) and eSOP (K) packages. See Appendix 1 for the part numbers.

REASON FOR CHANGE:

Improvement in the creepage between the high-voltage pin and the adjacent pin. Increased creepage enables the product to be more robust against external contamination inadvertently introduced during PCB assembly or in the field.

EFFECTIVE DATE: See Appendix 1 for sample availability and expected shipment dates by part numbers.

Please note that products with the above changes may begin to be shipped after the effective date without further notice. Products with the old pin configuration may continue to be shipped after the effective date until the inventory of old parts is fully depleted.

Appendix 1

Implementation Schedule by Part Numbers*

(Dates are approximate and subject to change. However, it will not be earlier than the dates as noted.)

Report Date: March 15, 2011

Report Last Updated On: NA

Part No.	Expected Shipment Date for Mass Production	Comments
TOP264KG	15-June-2011	
TOP264VG	15-June-2011	
TOP265KG	15-June-2011	
TOP265VG	15-June-2011	
TOP266KG	15-June-2011	
TOP266VG	15-June-2011	
TOP267KG	15-June-2011	
TOP267VG	15-June-2011	
TOP268KG	15-June-2011	
TOP268VG	15-June-2011	
TOP269KG	15-June-2011	
TOP269VG	15-June-2011	
TOP270KG	15-June-2011	
TOP270VG	15-June-2011	
TOP271KG	15-June-2011	
TOP271VG	15-June-2011	
LNK457KG	15-June-2011	
LNK457VG	15-June-2011	
LNK458KG	15-June-2011	
LNK458VG	15-June-2011	
LNK460KG	15-June-2011	
LNK460VG	15-June-2011	

Note: If any customer wishes to receive samples, please send a request within 2 weeks of this notification. Reasonable accommodations in a case-specific manner will be made by PI to provide sample prior to the shipment on a mass production scale.